

Atty Docket N .: JCLA6968

Serial N .: 09/838,752

a chip, located on a surface of the die pad, wherein the chip has an active surface and a corresponding back surface that are connected to each other via a plurality of side surfaces, wherein the active surface has beveled edges;

an adhesive material, attaching the back surface of the chip to the surface of the die pad, wherein the adhesive material covers the whole back surface of the chip and the side surfaces of the chip, the beveled edges of the active surface preventing a coverage of the active surface by the adhesive material;

a plurality of wires, electrically connecting the leads of the carrier to the active surface of the chip; and

a molding compound, covering the chip, the wires and a portion of the leads.

14. (Once amended) A package of a semiconductor device, the package comprising:

a carrier, having a die pad and a plurality of leads;

a plurality of chips, each chip having an active surface and a corresponding back surface that are connected to each other via a plurality of side surfaces, and the active surface has beveled edges, wherein the chips are stacked on one another on the die pad in such a manner that the active surface of one chip faces the back surface of one chip adjacently stacked thereon;

an adhesive material, respectively attaching the chips to one another and to the die pad, wherein the adhesive material respectively covers the whole back surface and the side surfaces of the chips, the beveled edges preventing a coverage of the corresponding active surfaces by the adhesive material;

a plurality of wires, electrically connecting the leads of the carrier to the respective active

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surfaces of the chips; and

a molding compound, covering the chips, the wires and a portion of the leads.